

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HIDEKI ISHIHARA	06/01/2021
MASAMI FUKUSHIMA	06/01/2021
KOICHI KITAGISHI	06/01/2021
SEIJIN NAKAYAMA	06/01/2021
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17432654
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<b>SIGNATURE:</b>	/Melanie A. Brunow/
<b>DATE SIGNED:</b>	08/20/2021
<b>Total Attachments: 2</b>	
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## ASSIGNMENT

WHEREAS, we, **Hideki Ishihara** of Kanagawa, Japan, **Masami Fukushima** of Tokyo, Japan, **Koichi Kitagishi** of Tokyo, Japan, and **Seijin Nakayama** of Tokyo, Japan, have made certain inventions which are described in U.S. Patent Application No. 17/432,654 for Letters Patent of the United States filed August 20, 2021, entitled **CENTRAL PROCESSING UNIT**, which claims priority to International Application No. PCT/JP2020/004528 filed February 6, 2020, and further described in Japanese Patent Application No. 2019-033586 filed February 27, 2019, and

WHEREAS, **UNO Laboratories, Ltd.** (hereinafter referred to as said Company), a Japanese corporation, having a place of business at 3-3-23-303, Sendagaya, Shibuya-ku, Tokyo 1510051 Japan, is desirous of acquiring the entire interest in said inventions throughout the United States of America and the territories thereof, for all other countries and under all international agreements,

NOW THEREFORE, for and in consideration of One Dollar (\$1.00) in hand paid, and other good and valuable consideration, receipt whereof is hereby acknowledged, we hereby sell, assign, and transfer unto said Company, its successors and assigns, the entire right, title and interest throughout the United States of America and the territories thereof and for all foreign countries, in and to said inventions, the aforesaid application, all prior, related United States provisional applications, and all other applications hereafter filed in the United States or any other country based in whole or in part on said inventions, and all Letters Patent granted upon said application by the United States or any other country, and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said Company. We further grant to said Company, its successors and assigns, the right to claim for any of said applications the full benefits and priority rights of any international agreement between the United States and any foreign country or countries.

We hereby warrant that we have the full right to make the conveyance herein, and we hereby covenant that we, our heirs, legal representatives and assigns, will, when requested, communicate to said Company, its representatives, successors and assigns, all facts known respecting said inventions, execute all divisional, continuing, reissue, reexamination and foreign applications together with individual assignments therefore, make all rightful oaths, sign all lawful papers, testify in any legal proceeding and generally do everything possible to aid said Company, its successors and assigns, in the obtaining of Letters Patent.

IN TESTIMONY WHEREOF, we have hereunto set our hand on the dates indicated with our signatures.

Date: June 1, 2021

Hideki Ishihara  
Hideki Ishihara

WITNESSES:

K. Yabuchi

H. Minomita

Date: June 1, 2021

Masami Fukushima  
Masami Fukushima

WITNESSES:

K. Yabuchi

H. Minomita

Date: June 1, 2021

Koichi Kitagishi  
Koichi Kitagishi

WITNESSES:

K. Yabuchi

H. Minomita

Date: June 1, 2021

Seijin Nakayama  
Seijin Nakayama

WITNESSES:

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